



<b>Session Title:</b>	<b>[WF1] Frontier Metrology and Modeling VI</b>
<b>Session Date:</b>	<b>November 22 (Wed.), 2023</b>
<b>Session Time:</b>	<b>09:00-10:00</b>
<b>Session Room:</b>	<b>Room F (Sicily Room, 1F)</b>
<b>Session Chair:</b>	<b>Prof. Tae-Hun Shim (Hanyang Univ., Korea)</b>

[WF1-1] [Invited]

09:00-09:30

Laser COOL Forming<sup>1</sup> TGV for Glass Substrate of Semiconductor Packaging and Laser COOL Cut<sup>1</sup> without Crack for Wafer(SiC, GaN, TSV, Sapphire)

Seak-Joon Lee (ITI, Korea)

[WF1-2] [Invited]

09:30-10:00

Flying-over Scanning Holography for Industrial Inspection

Seungram Lim, Kyungbeom Kim, Dong Hwan Im, Tae Woong Kim (Sejong Univ., Korea),  
Youseok Kim, Eungjoon Lee, Jae Ho Lee, and Taegeun Kim (Cubixel Inc., Korea)